appl. no. 10/796,427

May 13, 2006

To: Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761

28 Davis Avenue

Poughkeepsie, N.Y. 12603

Subject:

Serial No.

10/796,427

03/09/04

**MOU-SHIUNG LIN** 

"WIREBOND PAD FOR SEMICONDUCTOR CHIP

OR WAFER"

Grp. Art Unit: 2822

LEWIS, MONICA

## RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Office Action mailed Mar. 13, 2006, please consider the remarks as follows:

## **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 15, 2006.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date SITU